

## **General Description**

With human-machine interfacing requiring ever higher functionality and intuitiveness, touch panel type interfaces are rapidly becoming the norm for the new millennium.

TC332 is a 2 channel capacitive sensing device. The device can operate as a controller for 2 keys.

### **Features**

П	The	device	controls	2 com	nletely	z inde	nendent	touch	sensing	kevs
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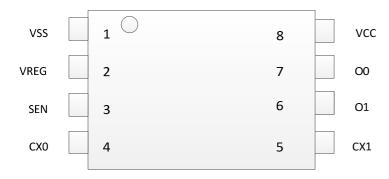
- ☐ Autocal for life no adjustments required
- ☐ System cost reduction
- ☐ Reliability through reducing system complexity
- ☐ Embedded noise immunity circuit
- ☐ RoHS compliant SO-8 package

## **Applications**

☐ Media	Players
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- ☐ Consumer Electronics
- ☐ Home appliances
- ☐ Keypads
- ☐ Mechanical switch replacement
- ☐ Sealed control panels, keypads

## Pin Diagram



## **Pin Description**

Pin	Name	I/O	Description	
1	VSS	Ground	Supply Ground	
2	VREG	Analog Output	Reference output	
3	SEN	Analog I/O	Sensitivity Set	
4	CX0	Analog I/O	Sensor pad for chanel0	
5	CX1	Analog I/O	Sensor pad for chanel1	
6	01	Digital Output	Output for CX1(open-drain)	
7	O0	Digital Output	Output for CX0(open-drain)	
8	VCC	Pwr	Power in	
Pin	Name	I/O	Description	

#### SEN

Sensitivity set pin, the capacitance range is  $15pf \sim 100pf$ . The smaller the value the higher the sensitivity **VREG** 

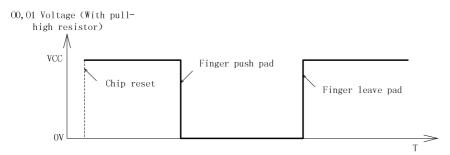
Reference voltage output, connected to 4.7nf capacitance.

#### CX0, CX1

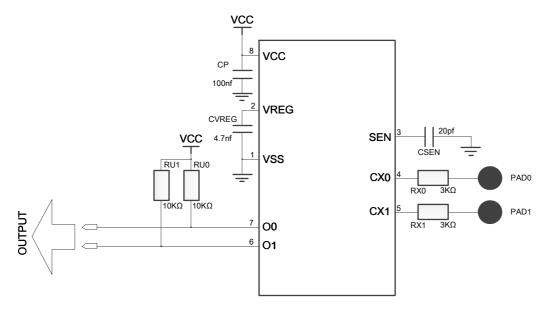
Capacitive sense pins connected to electrodes. Series resistance is  $3K\Omega$ .

#### 00, 01

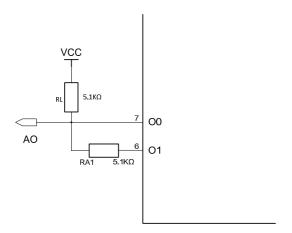
Parallel output ports of CX0~CX1 respectively. The structure of these parallel output ports is open drain NMOS for active low output level operation.



# **Application Circuit**



# **Analog Voltage Output**



KEY	O0	01	Voltage of AO
KEY0(CX0) Pushed	LOW	High-z	0v
KEY1(CX1) Pushed	High-z	LOW	0.5*VCC
NO KEY	High-z	High-z	VCC



### **PCB Layout Notice**

- 1. VCC and VSS power line should be drawn alone, and can not share power line with other chips(micro-controller and LCD driver,etc.). So as to prevent the chip from being affected by noise signal going throng the power line.
- 2. CP, CVREG, CSEN these three capacitances should be placed as close as possible to the chip. And the series resistors on wire of sense pad should also be placed as close as possible to the chip.
  - 3. The larger area of grounded copper, the more immunity to noise Interference.
  - 4. The sense traces and pad should be paid more attention to. The chip should be placed as close as possible to sense pad. The sense traces should be drawn to sense pad directly. The length of the different sense traces is not necessarily equal. The width of sense traces should be as small as possible. There should not be other power line and signal traces around the sense trace. If it can not be avoided, the other traces should cross the sense trace vertically. The distance between sense pads should be greater than 5mm. The distance between sense pad and grounded copper should be greater than 1.5mm.

## **Absolute Maximum Rating \***

Operating temperature  $-40 \sim +85^{\circ}\text{C}$ Storage temp  $-50 \sim +150^{\circ}\text{C}$ VCC  $-0.3 \sim +6.5\text{V}$ Max continuous pin current, any control or drive pin  $\pm 10\text{mA}$ 

Voltage forced onto any pin  $-0.3V \sim (Vcc+0.3)$  Volts

<sup>\*</sup> NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.



## **Electrical Characteristics**

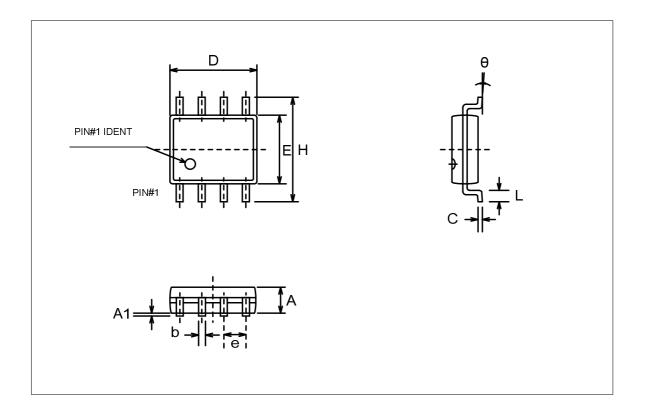
TA = 25°C

Characteristics	Symbo	Condition	Min	Тур	Max	Units
Operating voltage	Vcc		2.5		6.5	V
Current	ldd	VCC=5.0V		1.0		mA
consumption		VCC=3.0V		550		uA
Self calibration time	Tini			120		ms
after chip reset						
Range of	CX				2.5*CSEN	
capacitance on Pad						
Output impedance	Zo	Low voltage		50		Ohm
(open drain)		Hi-z		100M		
Output sink current	Isk	VCC=5V			10.0	mA
Minimum detective	delta_	CSEN=15pf		0.2		pF
capacitance	CX					
difference						
Sample cycle	Tsi	Normal		4.5		ms
		working				
		state				

### **ESD Characteristics**

Mode	Polarity	Max	Reference	
		8000V	VDD	
H.B.M	POS/NEG	V0008	VSS	
		V0008	P to P	
		500V	VDD	
M.M	POS/NEG	500V	VSS	
		500V	P to P	

# Package Diagram (SO-8)



Symbol	Dimen	sions In Milli	meters	Dimensions In Inches			
Symbol	Min	Nom	Max	Min	Nom	Max	
Α	1.30	1.50	1.70	0.051	0.059	0.067	
A1	0.06	0.16	0.26	0.002	0.006	0.010	
b	0.30	0.40	0.55	0.012	0.016	0.022	
С	0.15	0.25	0.35	0.006	0.010	0.014	
D	4.72	4.92	5.12	0.186	0.194	0.202	
Е	3.75	3.95	4.15	.0148	0.156	0.163	
е		1.27			0.050		
Н	5.70	6.00	6.30	0.224	0.236	0.248	
L	0.45	0.65	0.85	0.018	0.026	0.033	
θ	0°		8°	0°		8°	